

SPMZ2002DT1 :Part Detail

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General Information

Part Number	SPMZ2002DT1
Description	TEMPERATURE COMP M-PAK
Product Line	XM2001D
PTI	AKPF
Material Type	Tested Packaged Device
Life Cycle Description (code)	PRODUCT MATURITY/SATURATION
Status	Active
Application/Qualification Tier	10-YEARS APPLICATION LIFE

Package Information

Package Type and Termination Count	Sensor 5
Package Description and Mechanical Drawing	SNSR M-PAK 05
Device Weight(g)	0.39030
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	0.330
Package Width (nominal)(mm)	0.250
Package Thickness (nominal)(mm)	4.060
Maximum Height Above Board(mm)	4.200
Tape & Reel	Yes

Environmental and Compliance Information

Pb-Free	
RoHS Compliant	
Material Composition Declaration (MCD)	Download MCD Report Download MCD Report
RoHS Certificate of Analysis (CoA)	Contact Us
2nd Level Interconnect	Contact Us

Peak Package Body Temperature (PPT)(°C)	250
Maximum Time at Peak Temperature (s)	30
Number of Reflow Cycles	3
REACH SVHC	NXP REACH Statement

Manufacturing Information

Micron Size(μm)	6
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Ordering Information

Minimum Package Quantity (MPQ)	1000
MPQ Container	REEL
Exempt from Minimum Delivery Value	No
Preferred Order Quantity (POQ)	2000
POQ Container	BOX
Export Control Classification Number (US)	EAR99
Harmonized Tariff (
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US Currency)	-

Order

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
14572A	Update Notification	NEW PREMOLDED LEADFRAME SUPPLIER	19 Dec 2011	13 Jun 2012
14572	Product Change Notice	NEW PREMOLDED LEADFRAME SUPPLIER PRESSURE SENSORS SIFEL GEL CONVERSION - UNCOMPENSATED, COMPENSATED AND INTEGRATED	10 Oct 2011	07 Apr 2012
14266	Product Change Notice	NEW PREMOLDED LEADFRAME SUPPLIER FOR PRESSURE SENSOR PRODUCTS PRESSURE SENSORS SIFEL GEL CONVERSION - UNCOMPENSATED, COMPENSATED AND INTEGRATED	14 Apr 2011	11 Oct 2011
P14572	Product Alert	NEW PREMOLDED LEADFRAME SUPPLIER FOR PRESSURE SENSOR PRODUCTS PRESSURE SENSORS SIFEL GEL CONVERSION - UNCOMPENSATED, COMPENSATED AND INTEGRATED	12 Apr 2011	12 Apr 2011
P14266	Product Alert	NEW PREMOLDED LEADFRAME SUPPLIER FOR PRESSURE SENSOR PRODUCTS PRESSURE SENSORS SIFEL GEL CONVERSION - UNCOMPENSATED, COMPENSATED AND INTEGRATED	09 Jul 2010	09 Jul 2010

Operating Characteristics

Sample Exception Availability N

[Reliability Data Lookup](#)

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